

PATENT

Attorney Docket No.: 50623-00041

**AMENDMENTS TO THE SPECIFICATION:**

Please replace paragraph 22 with the following replacement paragraph.

Each repetition can be followed by removal of a significant amount of the solvent(s). The removal of the solvent(s) can be performed following a waiting period of about 0.1 second to about 5 seconds after the application of the coating composition so as to allow the liquid sufficient time to flow and spread over the stent surface before the solvent(s) is removed to form a coating. The waiting period is particularly suitable if the coating composition contains a volatile solvent, such as solvents having boiling points ~~>130°C~~ <130°C at ambient pressure, since such solvents are typically removed quickly.

Please replace paragraph 24 with the following replacement paragraph.

In one embodiment, the stent can be warmed to a temperature of from about 35°C to about 80°C prior to the application of the coating composition so as to facilitate faster removal of the solvent(s). The particular temperature selected depends, at least in part, on the particular active agent employed in the coating composition. By way of example, pre-heating of the stent prior to applying a composition containing actinomycin D should be performed at a temperature not greater than about 55°C. Pre-heating is particularly suitable for embodiments in which the solvent(s) employed in the coating composition has a high boiling point, i.e., non-volatile solvents having boiling points of, for example, >130°C at ambient pressure (e.g., dimethylsulfoxide (DMSO), dimethylformamide (DMF), and dimethylacetamide (DMAC)).

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Please insert the following paragraph before paragraph 25 of the specification.

Another embodiment encompasses a method of coating an implantable device comprising heating the implantable device; applying a composition including a fluid to the warm implantable device; and directing a gas onto the implantable device to induce evaporation of the fluid from the composition to form a coating on the implantable device.